

Crystal LTD TM SPEC Form

Customer

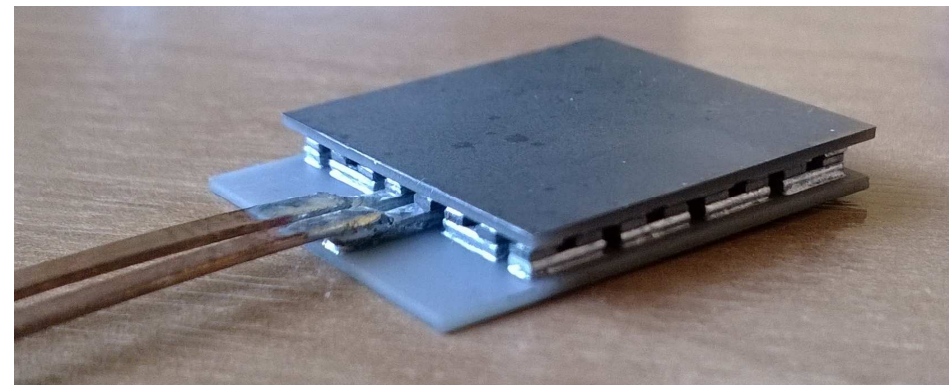
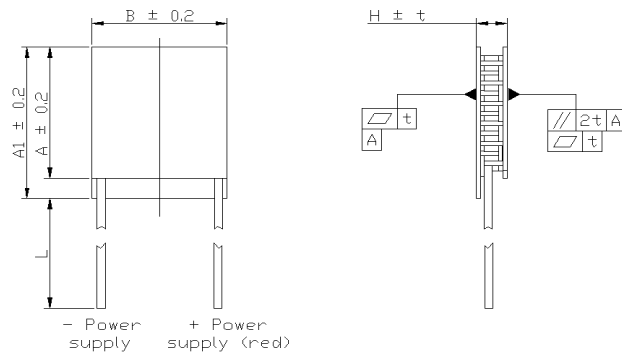
PO#

PO date

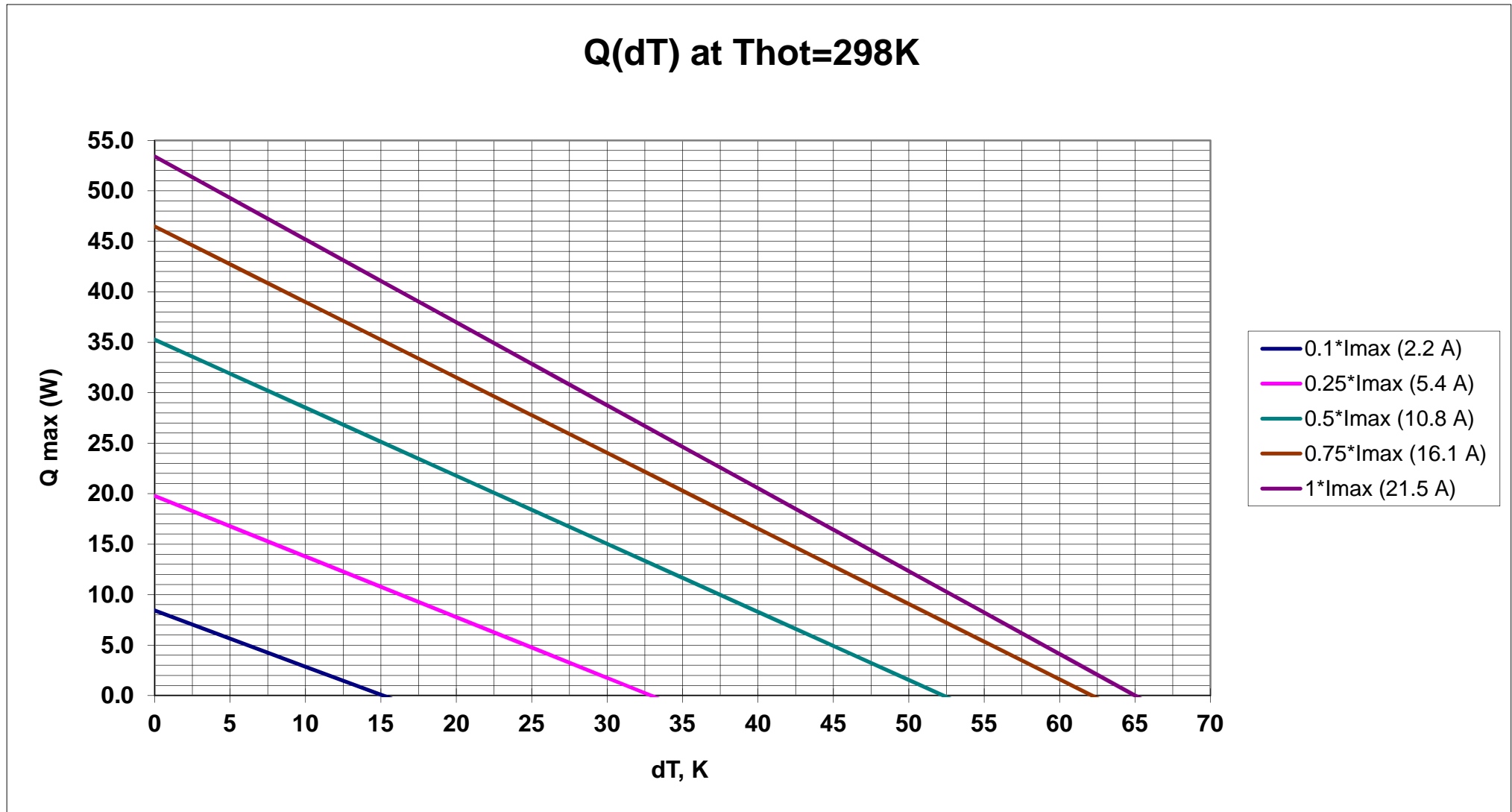
Thermoelectric module (TM) specification

PO position #	TM	Internal Solder Melting Temp, C	Max operating temperature, °C		Parameters in vacuum at hot side temperature 25 °C				Rac at 25 °C		Ceramic size, mm		TM Height		Wire			Sealing
			short time	continuous operation	I <sub>max</sub> , A	U <sub>max</sub> , V	Q <sub>max</sub> , W	dT <sub>max</sub> , K	Rac, Ohm	Tolerance ±, %	A/A1	B	Height, mm	Tolerance t, ± mm	S, mm <sup>2</sup>	Length, mm	Tolerance ±, mm	
1	S-032-14-045-Mch	180	150	115	21.5	4.1	53.4	65.0	0.15	10	20/24	20	3.30	0.2	1.4x0.8	100	5	
	AIN ceramics, both sides metallized non-RoHS														solid copper not tinned uninsulated			

Clamping force: 7.6 - 15.1 kg



Max dT is reduced by 2-3K for silicon sealed and 1-2K for epoxy sealed versions.



### U(dT) at Thot=298K

